

Title (en)
WAVE SOLDERING DEVICE

Title (de)
VORRICHTUNG ZUM WELLENLÖTEN

Title (fr)
DISPOSITIF DE BRASAGE A LA VAGUE

Publication
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Application
EP 05788651 A 20050927

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Abstract (en)
[origin: WO2006037520A1] The invention relates to a device for wave soldering workpieces (15), comprising means for moving the workpiece (15) that is to be soldered along a specific path across at least one solder wave (3, 4, 5, 6) generated above a solder reservoir (2), an inert gas atmosphere being created above the solder reservoir (2) so as to largely exclude oxygen. The path extends in such a way that at least one part of the workpiece (15) enters in contact with the solder wave (3, 4, 5, 6). A cap (1) as well as tubes (9, 13) for delivering the inert gas are provided below the workpiece (15). In order to prevent floods, two or more tubes (13) are provided with upward-facing holes or slots that are covered by U-shaped shielding housings (14) which are substantially open towards the bottom.

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